TOSHIBA Power Transistor Module Silicon NPN Epitaxial Type (Four Darlington Power Transistor in One)

MP4301

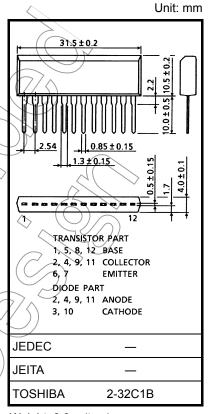
High Power Switching Applications

Hammer Drive, Pulse Motor Drive and Inductive Load Switching

- Small package by full molding (SIP 12 pin)
- High collector power dissipation (4 devices operation)
 PT = 4.4 W (Ta = 25°C)
- High collector current: IC (DC) = 3 A (max)
- High DC current gain: $h_{FE} = 2000$ (min) ($V_{CE} = 2$ V, $I_{C} = 1.5$ A)

Absolute Maximum Ratings (Ta = 25°C)

| Characteristics | | Symbol | Rating | Unit |
|-----------------------------|-------|------------------|------------|-------------------------------------|
| Collector-base voltage | | V_{CBO} | 120 | > v |
| Collector-emitter voltage | | V _{CEO} | 100 | V |
| Emitter-base voltage | | V _{EBO} | 6 | y |
| Collector current | DC | Ic | 3 | $\langle \langle A \rangle \rangle$ |
| | Pulse | ICP | 6 | 1 |
| Continuous base current | | IB |)) 0.5 | Α |
| Collector power dissipation | | Pc | 2.2 | \ w |
| (1-device operation) | | | 2.2 | |
| Collector power dissipati | on (| 7/ \PT | 4.4 | W |
| (4-device operation) | | | 4.4 | \rightarrow " |
| Junction temperature | | T_j | (150/) | °C |
| Storage temperature range | | T _{stg} | -55 to 150 | °C |

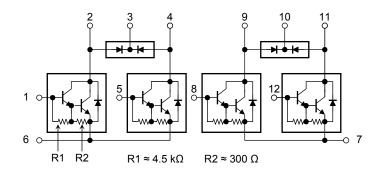


Weight: 3.9 g (typ.)

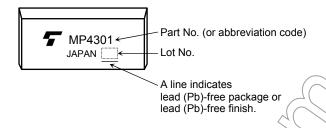
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Array Configuration



Marking



Thermal Characteristics

| Characteristics | Symbol | Max | Unit |
|---|------------------------|------|------------|
| Thermal resistance from junction to ambient | ΣR _{th (j-a)} | 28.4 | °C/W |
| (4-device operation, Ta = 25°C) | | | \wedge |
| Maximum lead temperature for soldering purposes | | 260 | % |
| (3.2 mm from case for 10 s) | 7/^ | | |
| | | (| $7/\wedge$ |

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Electrical Characteristics (Ta = 25°C)

| Charac | teristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|-----------------------|-------------------|-----------------------|---|------|-------|---------------|------|
| Collector cut-off cu | rrent | I _{CBO} | V _{CB} = 120 V, I _E = 0 A | _ | _ | 10 | μA |
| Collector cut-off cu | rrent | I _{CEO} | V _{CE} = 100 V, I _B = 0 A | _ | _ | 10 | μΑ |
| Emitter cut-off curre | ent | I _{EBO} | V _{EB} = 6 V, I _C = 0 A | 0.5 | _ | 2.5 | mA |
| Collector-base brea | akdown voltage | V (BR) CBO | I _C = 1 mA, I _E = 0 A | 120 | _ | _ | V |
| Collector-emitter bi | reakdown voltage | V (BR) CEO | I _C = 10 mA, I _B = 0 A | 100 |) / _ | _ | V |
| DC surrent sein | | h _{FE (1)} | V _{CE} = 2 V, I _C = 1.5 A | 2000 | _ | 15000 | |
| DC current gain | | h _{FE (2)} | V _{CE} = 2 V, I _C = 3 A | 1000 | _ | _ | _ |
| Saturation voltage | Collector-emitter | V _{CE} (sat) | I _C = 1.5 A, I _B = 3 mA | _ | _ | 1.5 | V |
| Saturation voltage | Base-emitter | V _{BE (sat)} | I _C = 1.5 A, I _B = 3 mA | _ | _ | 2.0 | |
| Transition frequence | cy | f _T | V _{CE} = 2 V, I _C = 0.5 A | _ | 60 | _ | MHz |
| Collector output ca | pacitance | C _{ob} | V _{CB} = 10 V, I _E = 0 A, f = 1 MHz | - / | <30 | \rightarrow | pF |
| | Turn-on time | t _{on} | Output | | 0.3 | <u> </u> | |
| Switching time | Storage time | t _{stg} | 20 µs | | 2.0 | _ | μs |
| | Fall time | t _f | $I_{B1} = -I_{B2} = 3 \text{ mA, duty cycle} \le 1\%$ |) _ | 0.4 | _ | |

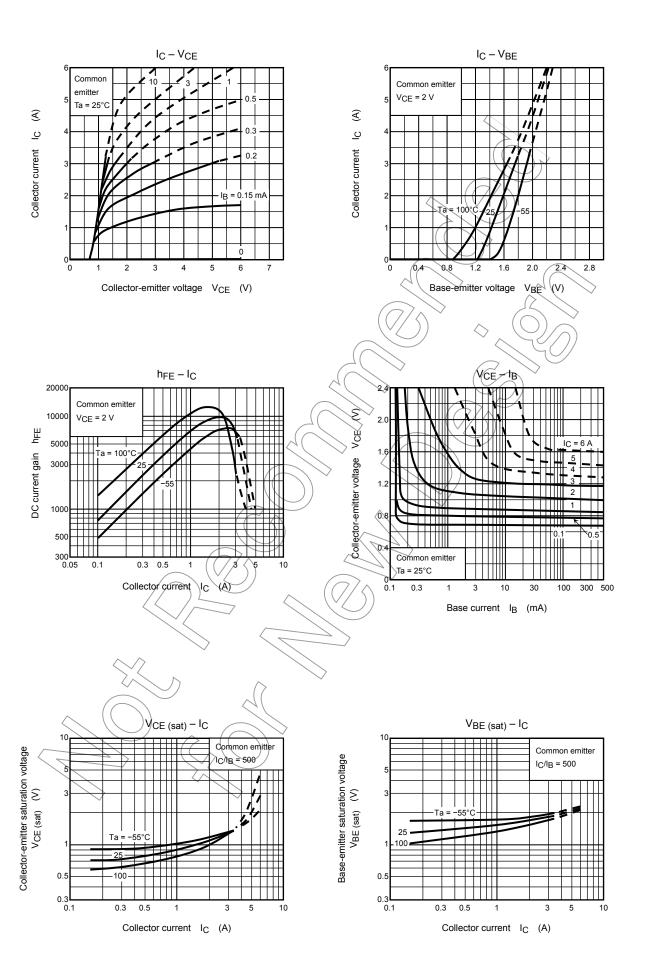
Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|-------------------------|---------------------|--|-----|------|-----|------|
| Maximum forward current | /\{1\ _{EM} | | _ | _ | 3 | Α |
| Surge current | UFSM | t = 1 s, 1 shot | _ | _ | 6 | Α |
| Forward voltage | √ V _F | 1 _F = 1 A, I _B = 0 A | _ | 1.2 | 1.8 | V |
| Forward voltage | t _{rr} | I _E = 3 A, V _{BE} = −3 V, dI _F /dt = −50 A/μs | _ | 1.0 | - | μs |
| Reverse recovery charge | Q _{rr} | 1E - 3 A, VBE3 V, αιτ/αι30 Ανμδ | _ | 5 | - | μC |

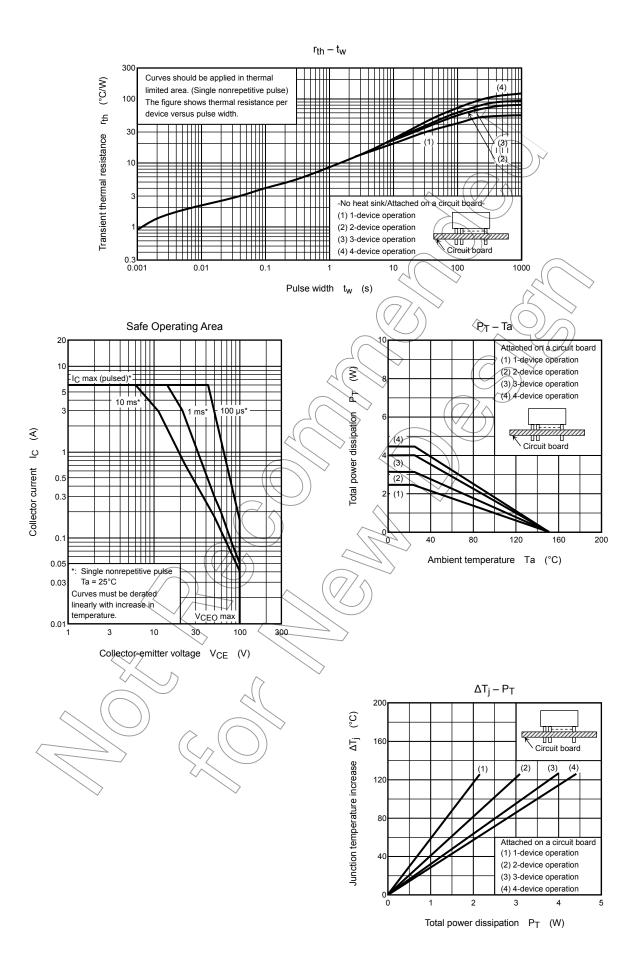
Flyback-Diode Ratings and Characteristics (Ta = 25°C)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|-------------------------|----------------|-------------------------|-----|------|-----|------|
| Maximum forward current | IFM | _ | _ | _ | 3 | Α |
| Reverse current | I _R | V _R = 120 V | _ | _ | 0.4 | μΑ |
| Reverse voltage | V _R | I _R = 100 μA | 120 | _ | _ | V |
| Forward voltage | VF | I _F = 0.5 A | _ | _ | 1.8 | V |

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RESTRICTIONS ON PRODUCT USE

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